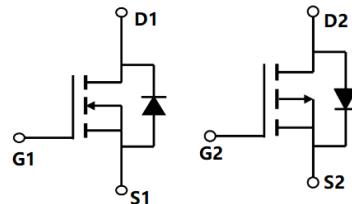
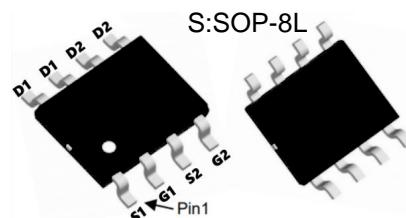
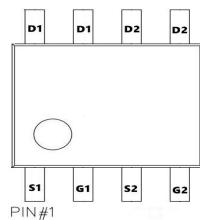


# TM026G04S

## N+P-Channel Enhancement Mode Mosfet

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>Low <math>R_{DS(ON)}</math></li> <li>RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>Load switch</li> <li>PWM</li> </ul>	<p><b>Product Summary</b></p> <p><b>N Channel</b>  <math>V_{DS} = 40V, I_D = 7.3A</math>  <math>R_{DS(ON)} = 26m\Omega</math>(typ.)@ <math>V_{GS}=10V</math></p> <p><b>P Channel</b>  <math>V_{DS} = -40V, I_D = -6.1A</math>  <math>R_{DS(ON)} = 56m\Omega</math>(typ.)@ <math>V_{GS}=-10V</math></p> <p>100% UIS Tested  100% <math>R_g</math> Tested</p>
--	---



Marking: 7004

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
$V_{DS}$	Drain-Source Voltage	40	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	7.3	-6.1	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.9	-3.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	26	-22	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	16.2	39	mJ
$I_{AS}$	Avalanche Current	6.8	-6.8	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.67	1.67	W
$T_{STG}$	Storage Temperature Range	-55 to 150	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	57		°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	30		°C/W

**TM026G04S**
**N+P-Channel Enhancement Mode Mosfet**
**N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40	44	---	V
△BVDSS/△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.034	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =5A	---	26	36	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A	---	36	49	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.56	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =5A	---	14	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	2.6	---	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A	---	5.5	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.25	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	2.5	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =20V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A	---	8.9	---	ns
T <sub>r</sub>	Rise Time		---	2.2	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	41	---	
T <sub>f</sub>	Fall Time		---	2.7	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz	---	593	---	pF
C <sub>oss</sub>	Output Capacitance		---	76	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	56	---	
I <sub>s</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	7.3	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	23	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=10A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**TM026G04S**
**N+P-Channel Enhancement Mode Mosfet**
**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	-44	---	V
$\Delta BVDSS/\Delta T_J$	$BVDSS$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.018	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-3\text{A}$	---	56	76	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-2\text{A}$	---	76	85	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.0	-1.5	-2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	2.5	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-40\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{DS}=-40\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm100$	nA
gfs	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-3\text{A}$	---	5.8	---	S
Qg	Total Gate Charge (-4.5V)	$V_{DS}=-32\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	6.4	---	nC
Qgs	Gate-Source Charge		---	2.1	---	
Qgd	Gate-Drain Charge		---	2.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-20\text{V}$ , $V_{GS}=-4.5\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	4.2	---	ns
Tr	Rise Time		---	23	---	
Td(off)	Turn-Off Delay Time		---	26.8	---	
Tf	Fall Time		---	20.6	---	
Ciss	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	620	---	pF
Coss	Output Capacitance		---	65	---	
Crss	Reverse Transfer Capacitance		---	53	---	
IS	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-6.1	A
ISM	Pulsed Source Current <sup>2,4</sup>		---	---	-16.1	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

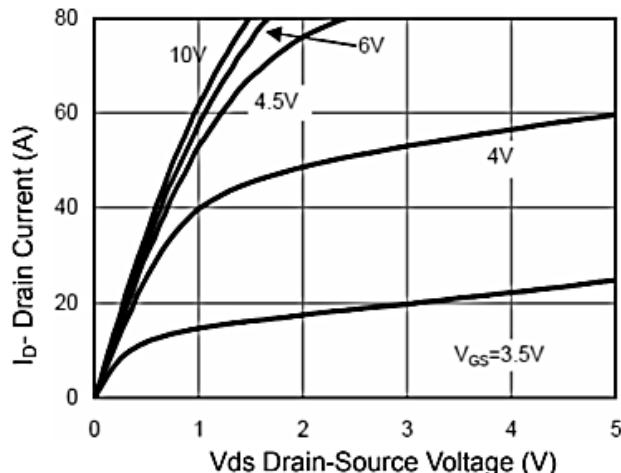
Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

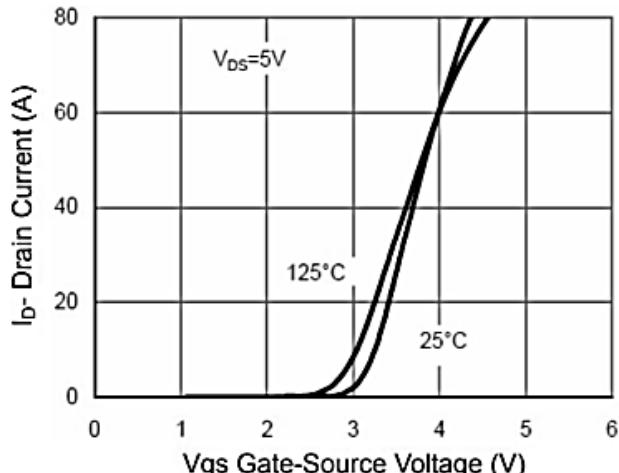
## TM026G04S

## N+P-Channel Enhancement Mode Mosfet

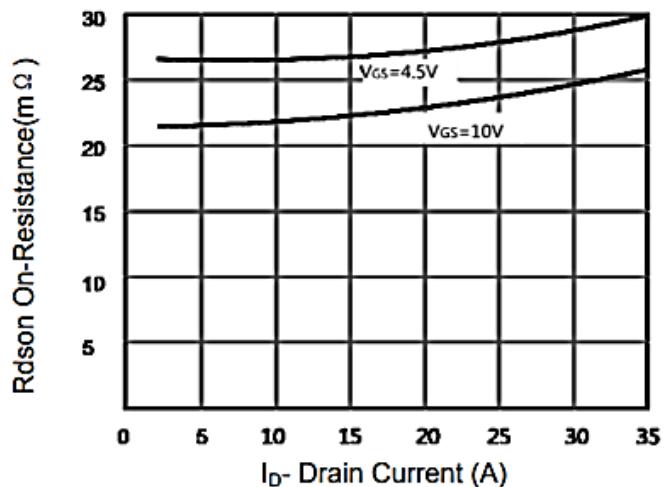
### N-Channel Typical Characteristics



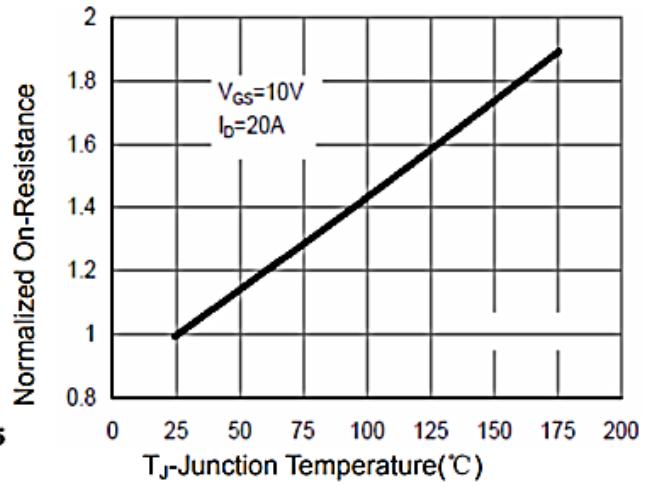
**Figure 1 Output Characteristics**



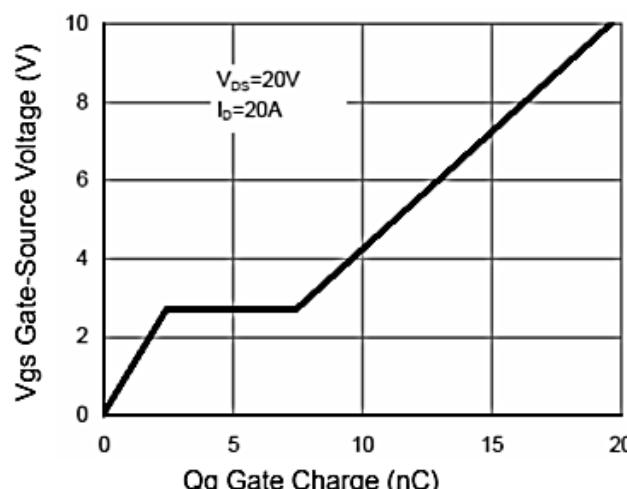
**Figure 2 Transfer Characteristics**



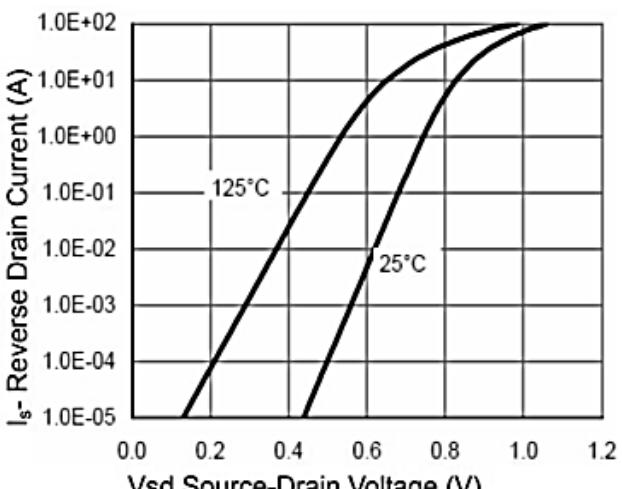
**Figure 3 Rdson- Drain Current**



**Figure 4 Rdson-Junction Temperature**



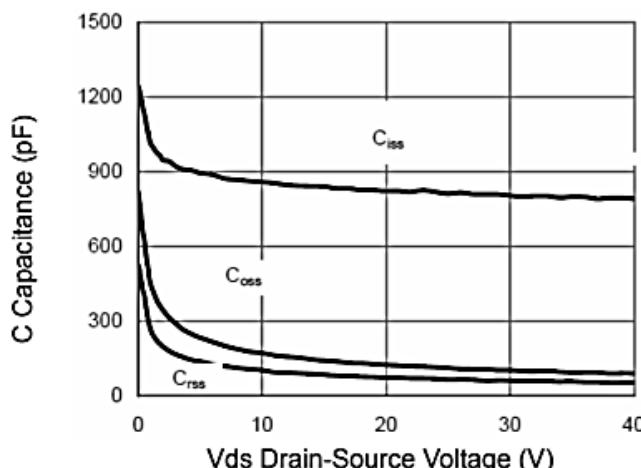
**Figure 5 Gate Charge**



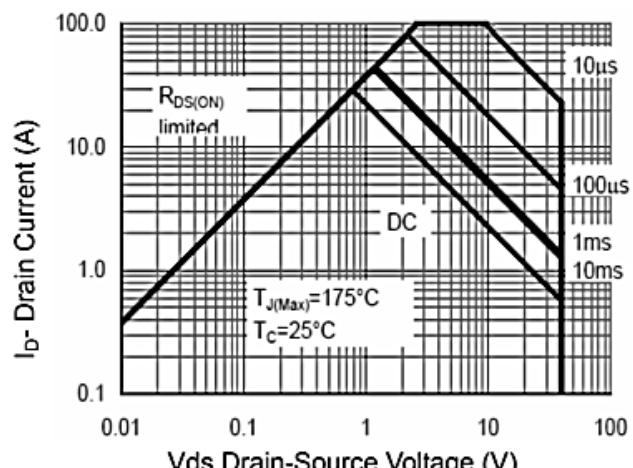
**Figure 6 Source- Drain Diode Forward**

## TM026G04S

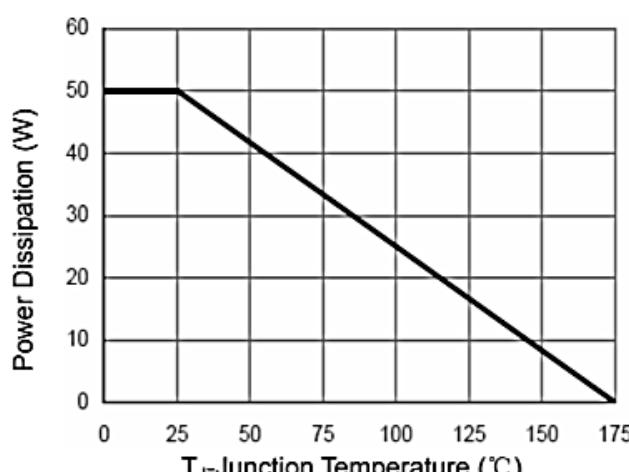
## N+P-Channel Enhancement Mode Mosfet



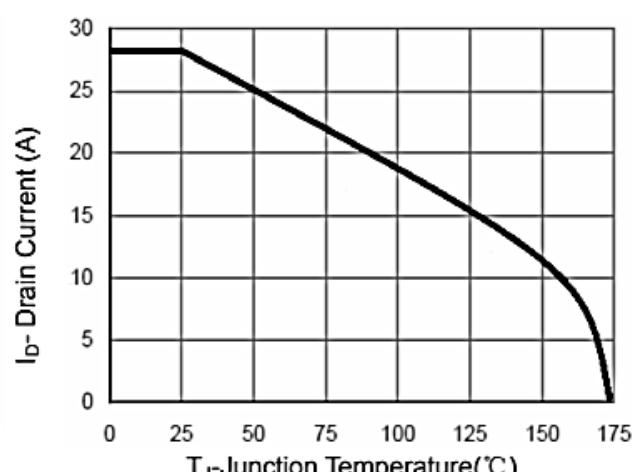
**Figure 7 Capacitance vs Vds**



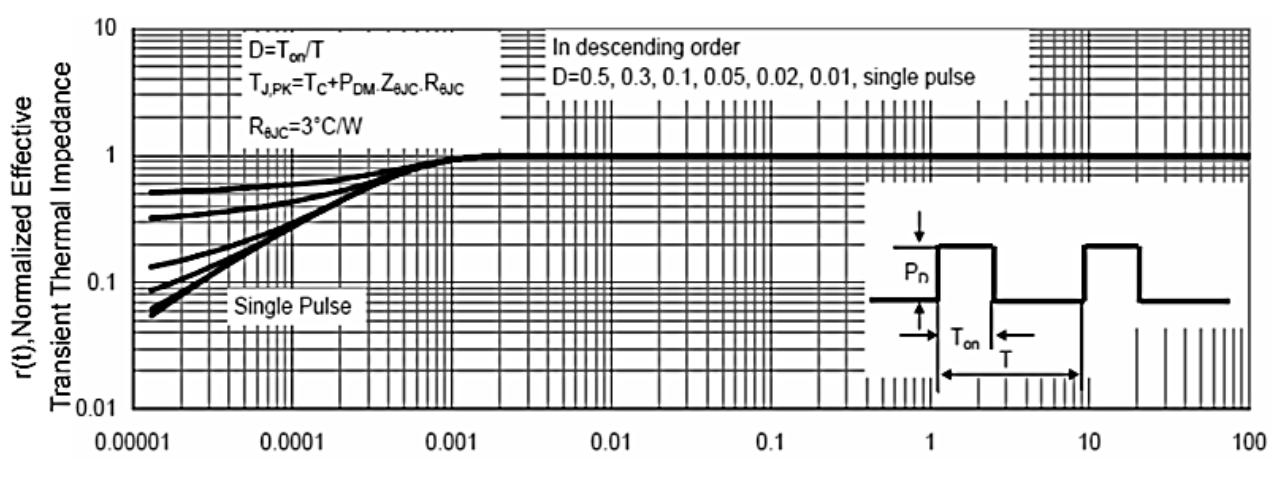
**Figure 8 Safe Operation Area**



**Figure 9 Power De-rating**



**Figure 10 I<sub>d</sub> Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TM026G04S

## N+P-Channel Enhancement Mode Mosfet

### P-Typical Characteristics

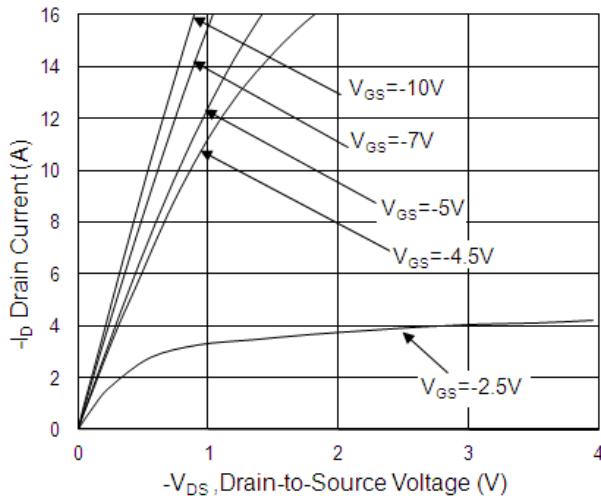


Fig.1 Typical Output Characteristics

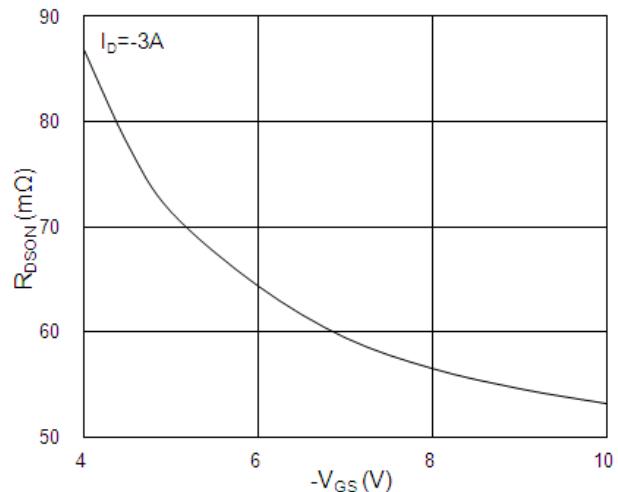


Fig.2 On-Resistance vs. G-S Voltage

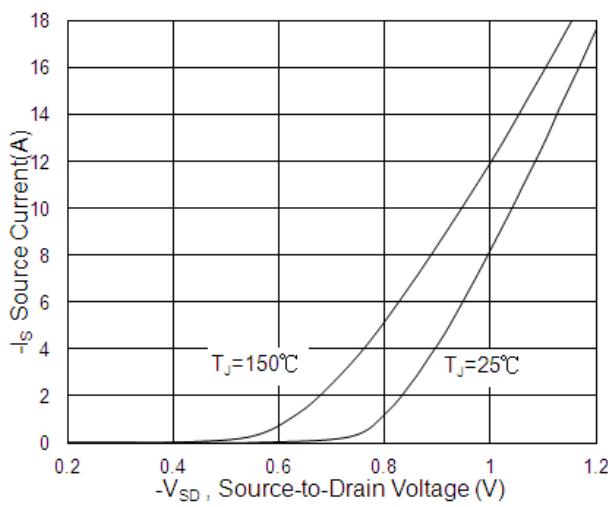


Fig.3 Forward Characteristics Of Reverse

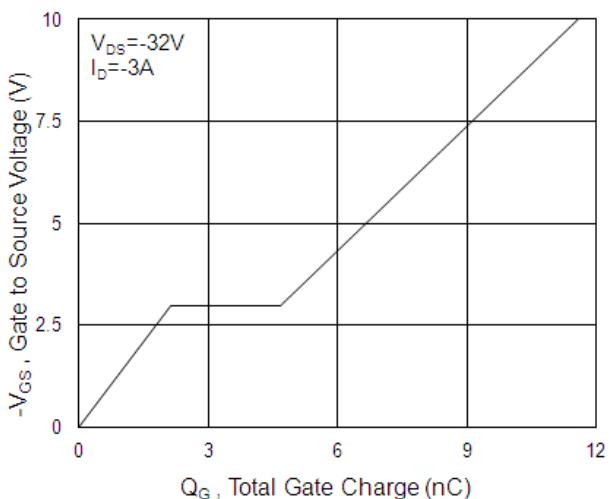


Fig.4 Gate-Charge Characteristics

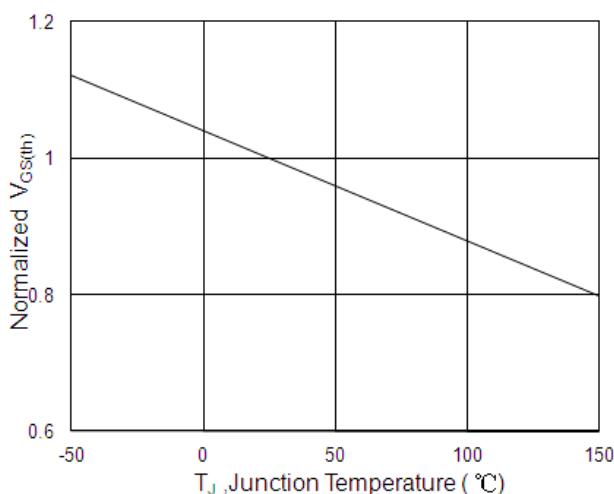


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

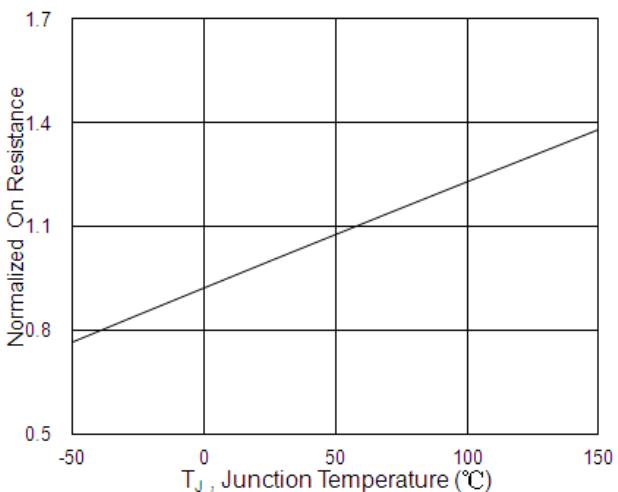
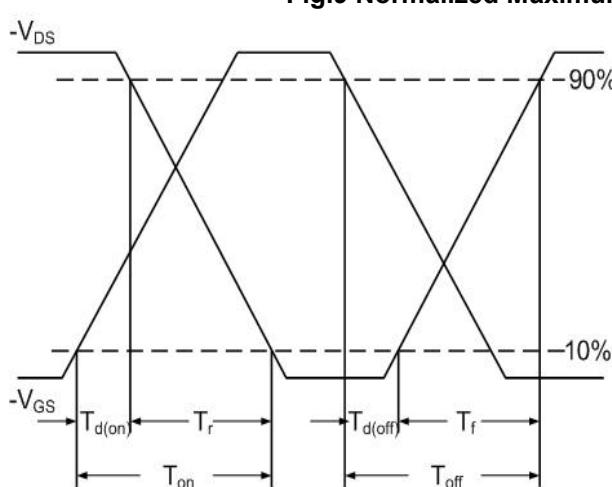
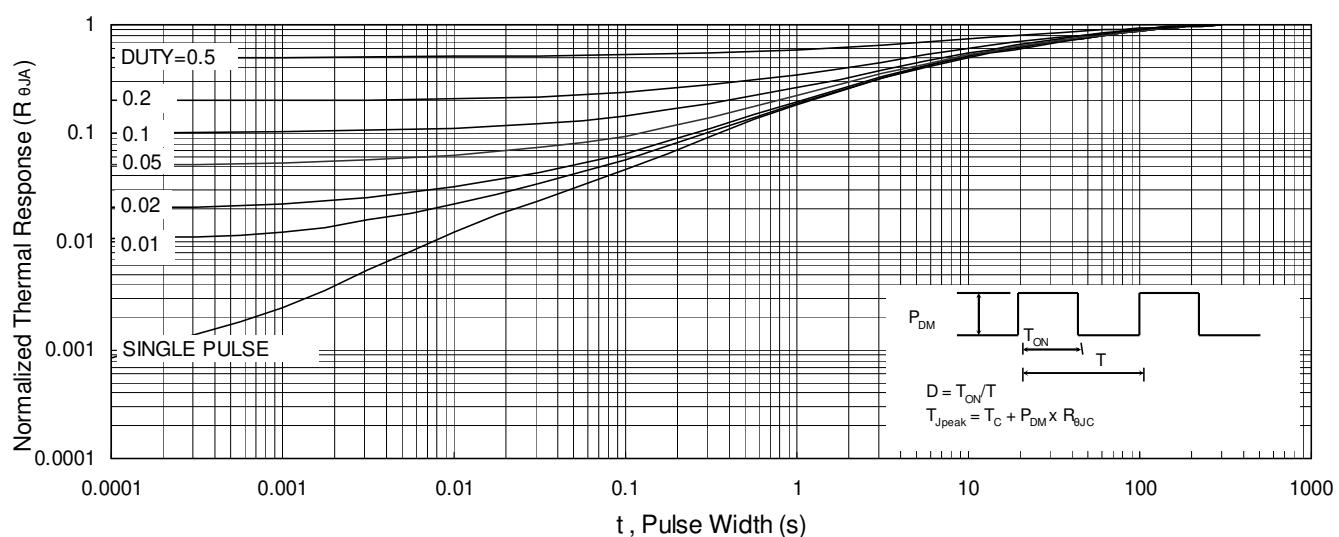
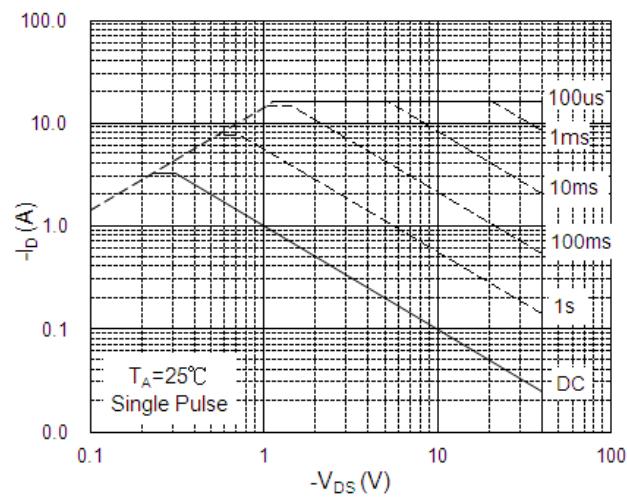
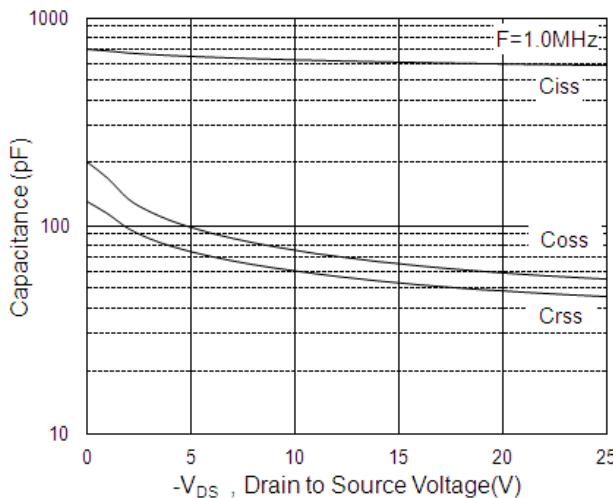


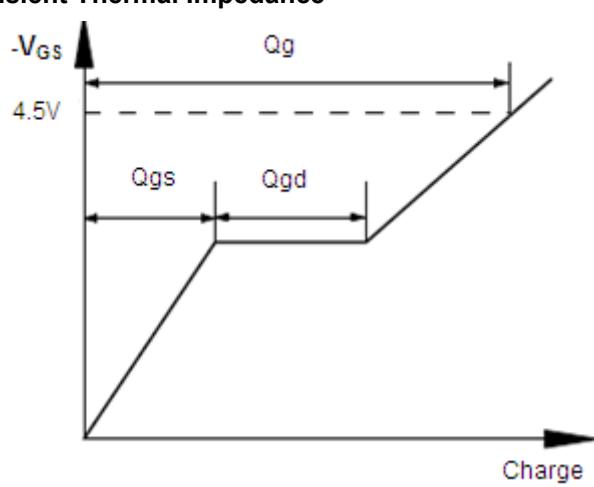
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

## TM026G04S

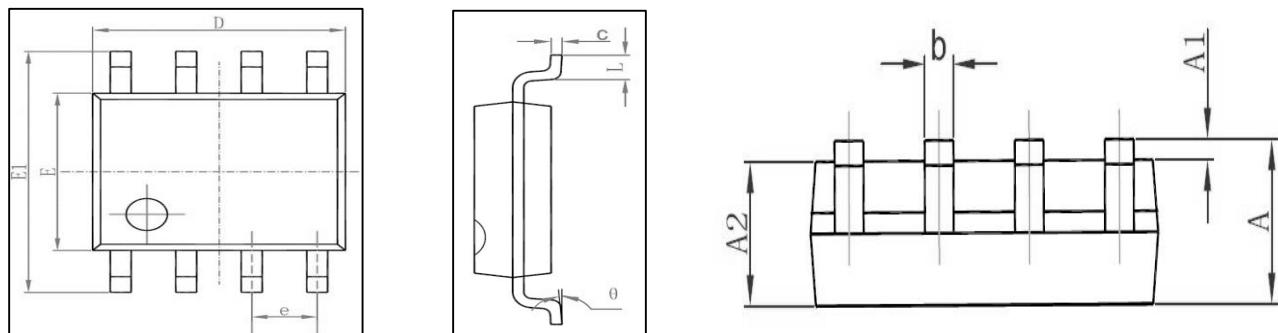
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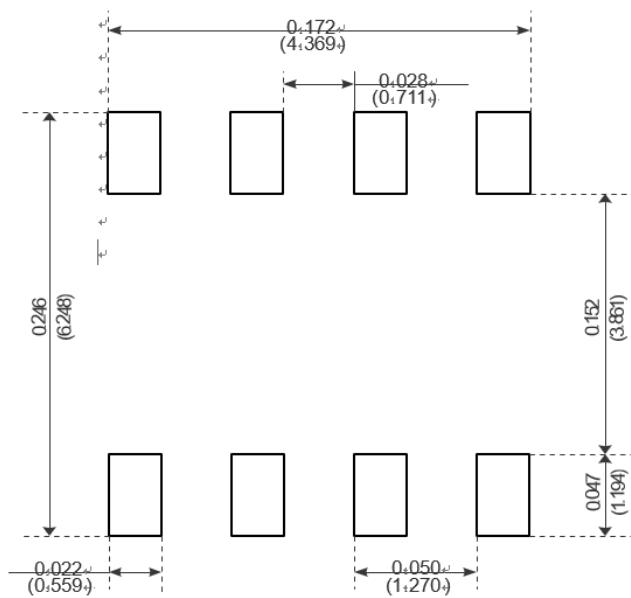
Data and specifications subject to change without notice.



## Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°



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